



Material Content Data Sheet



Sales Product Name		SAB-C165-L25M HA		Issued		29. August 2013		
MA#		MA000725082						
Package		PG-MQFP-100-2		Weight*		1786.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.388	0.97	0.97	9732	9732
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.03		301	
	inorganic material	silicon	7440-21-3	2.331	0.13		1304	
	non noble metal	nickel	7440-02-0	10.756	0.60		6020	
	non noble metal	copper	7440-50-8	344.917	19.30	20.06	193047	200672
wire	noble metal	gold	7440-57-5	3.175	0.18	0.18	1777	1777
encapsulation	organic material	carbon black	1333-86-4	6.911	0.39		3868	
	plastics	epoxy resin	-	200.412	11.22		112169	
	inorganic material	silicondioxide	60676-86-0	1174.831	65.76	77.37	657542	773579
leadfinish	non noble metal	tin	7440-31-5	19.520	1.09	1.09	10925	10925
plating	noble metal	silver	7440-22-4	1.857	0.10	0.10	1040	1040
glue	plastics	epoxy resin	-	1.016	0.06		569	
	noble metal	silver	7440-22-4	3.048	0.17	0.23	1706	2275
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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